

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	290	(lin with long with hui) or( powerchip adj semiconductor)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/08 09:36
L2	6	1 and (defect with control)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/08 09:49
L3	0	("2005/0049836").URPN.	USPAT	OR	OFF	2005/04/08 09:37
L4	0	("2005/0049836").URPN.	USPAT	OR	OFF	2005/04/08 09:38
L5	0	("2003/0060916").URPN.	USPAT	OR	OFF	2005/04/08 09:40
L6	11	("20020034326"   "4618938"   "5761064"   "6016562"   "6246787"   "6477685"   "6559662"   "6583634"   "6628817"   "6703850"   "6757621").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/04/08 09:40
L7	81	("4618938").URPN.	USPAT	OR	OFF	2005/04/08 09:46
L8	81	("4618938").URPN.	USPAT	OR	OFF	2005/04/08 09:46
L9	0	("6828776").URPN.	USPAT	OR	OFF	2005/04/08 09:47
L10	13	7 and (defect with control)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/08 09:50
L11	13	8 and (defect with control)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/08 09:50
L12	281	702/34.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/08 10:00
L13	9195	((classify\$3 or group\$3 or divid\$3 or separat\$3 or categoriz\$3 or sort\$3) with (defect\$1 or failure\$1 or fault\$1 or flaw\$1)) and (((semi adj conductor) or wafer\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) with (process\$3 or manufactur\$3 or fabricat\$3 or product\$3 or yield\$3))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/08 10:00
L14	71	L13 and (((pattern\$2 or model\$3 or prototyp\$3) with wafer\$1) same (first with defect\$1) same (second with defect\$1))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/08 10:00
L15	55	L13 and (((pattern\$2 or model\$3 or prototyp\$3) with wafer\$1 with defect\$1) same (first with defect\$1) same (second with defect\$1))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/08 10:01

L16	33	L15 and (defect\$1 near\$3 (type\$1 or group\$1 or categoriz\$3 or cluster\$1 or sets or class\$2))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/08 10:01
L17	2	"5862055".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/08 10:02
L18	1216	700/121.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/08 10:03
L19	122	18 and (((classify\$3 or group\$3 or divid\$3 or separat\$3 or categoriz\$3 or sort\$3) with (defect\$1 or failure\$1 or fault\$1 or flaw\$1)) and ((semi adj conductor) or wafer\$1 or (integrated adj circuit\$1) or chip\$1 or substrate\$1))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/08 10:03
S1	281	702/34.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/04 18:33
S2	22403	(((classify\$3 or group\$3 or divid\$3 or separat\$3 or categoriz\$3 or sort\$3) with (defect\$1 or failure\$1 or fault\$1 or flaw\$1)) and ((semi adj conductor) or wafer\$1 or (integrated adj circuit\$1) or chip\$1 or substrate\$1))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/08 10:03
S3	12458	(((classify\$3 or group\$3 or divid\$3 or separat\$3 or categoriz\$3 or sort\$3) with (defect\$1 or failure\$1 or fault\$1 or flaw\$1)) and (((semi adj conductor) or wafer\$1 or (integrated adj circuit\$1) or chip\$1 or substrate\$1) with (process\$3 or manufactur\$3 or fabricat\$3 or product\$3)))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/04 18:53
S4	7	S1 and S3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/04 18:43
S5	9191	(((classify\$3 or group\$3 or divid\$3 or separat\$3 or categoriz\$3 or sort\$3) with (defect\$1 or failure\$1 or fault\$1 or flaw\$1)) and (((semi adj conductor) or wafer\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) with (process\$3 or manufactur\$3 or fabricat\$3 or product\$3 or yield\$3)))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/04 18:55
S6	70	S5 and (((pattern\$2 or model\$3 or prototyp\$3) with wafer\$1) same (first with defect\$1) same (second with defect\$1))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/04 19:18

S7	55	S6 and (defect\$1 with (type\$1 or group\$1 or categor\$3 or cluster\$1 or sets or class\$2))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/04 19:06
S8	43	S6 and (defect\$1 near3 (type\$1 or group\$1 or categor\$3 or cluster\$1 or sets or class\$2))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/04 19:19
S9	54	S5 and (((pattern\$2 or model\$3 or prototyp\$3) with wafer\$1 with defect\$1) same (first with defect\$1) same (second with defect\$1))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/04 19:18
S10	32	S9 and (defect\$1 near3 (type\$1 or group\$1 or categor\$3 or cluster\$1 or sets or class\$2))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/04 19:19
S11	2	S10 and (database with rule\$1 with (defect\$1 near2 type\$1))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/04 19:22
S12	0	S5 and ((in adj line) with (automatic adj defect adj classification))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/04 19:24
S13	114	S5 and ((automatic adj defect adj classification))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/04 19:24
S14	0	S5 and ((automatic adj defect adj classification) same (in adj line))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/04 19:25
S15	9	S5 and ((automatic adj defect adj classification) and (in adj line))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/04 19:41
S16	0	S5 and (killer same (root with cause with analysis) same correct\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/04 19:42
S17	21	S5 and ( (root with cause with analysis) same correct\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/08 10:02

S18	1	S5 and ( (root with cause with analysis) same correct\$3) and (killer with defect\$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/04 19:42
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